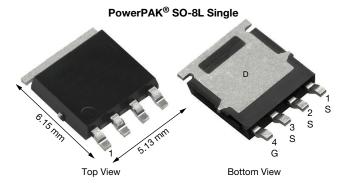
SQJ403BEEP



Vishay Siliconix

Automotive P-Channel 30 V (D-S) 175 °C MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	-30			
$R_{DS(on)} (\Omega)$ at $V_{GS} = -10 V$	0.0085			
$R_{DS(on)} (\Omega)$ at $V_{GS} = -4.5 V$	0.0200			
I _D (A)	-30 ^a			
Configuration	Single			
Package	PowerPAK SO-8L			

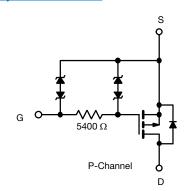


FEATURES

- TrenchFET® power MOSFET
- ESD protection: 3000 V
- AEC-Q101 qualified
- 100 % R_g and UIS tested
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>



RoHS COMPLIANT HALOGEN FREE



ABSOLUTE MAXIMUM RATING	S (T _C = 25 °C, unless	otherwise noted)		
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		V _{DS}	-30	V	
Gate-Source Voltage		V _{GS}	± 20		
Continuous Drain Current ^a	T _C = 25 °C	- I _D	-30		
	T _C = 125 °C		-30		
Continuous Source Current (Diode conduction) ^a		ا _S	-30	А	
Pulsed Drain Current ^b		I _{DM}	-84		
Single Pulse Avalanche Current	L = 10 mH	I _{AS}	-6.5		
Single Pulse Avalanche Energy		E _{AS}	211	mJ	
Maximum Power Dissipation ^b	T _C = 25 °C	PD	68	W	
	T _C = 125 °C	۳D	22		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55 to +175	°C	
Soldering Recommendations (Peak temperature) ^{d, e}			260	C	

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	LIMIT	UNIT	
Junction-to-Ambient	PCB mount ^c	R _{thJA}	68	°C/W	
Junction-to-Case (Drain)		R _{thJC}	2.2	0/00	

Notes

- a. Package limited.
- b. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.
- c. When mounted on 1" square PCB (FR4 material).

d. See solder profile (<u>www.vishay.com/doc?73257</u>). The end of the lead terminal of PowerPAK SO-8L is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.

e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.

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PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static						<u> </u>		
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V, I_D = -250 \mu A$		-30	-	-	V	
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	V _{GS} , I _D = -250 μA	-1.5	-2.0	-2.5	v	
Osta Osuma Laskana		$V_{DS} = 0 V, V_{GS} = \pm 12 V$		-	-	± 2	μA	
Gate-Source Leakage	$V_{\rm DS} = 0 \text{ V}, V_{\rm GS} = \pm 20 \text{ V}$		-	-	± 1	mA		
Zero Gate Voltage Drain Current		$V_{GS} = 0 V$	V _{DS} = -30 V	-	-	-1		
	I _{DSS}	$V_{GS} = 0 V$	V _{DS} = -30 V, T _J = 125 °C	-	-	-50	μA	
		$V_{GS} = 0 V$	V_{DS} = -30 V, T_{J} = 175 °C	-	-	-250		
On-State Drain Current ^a	I _{D(on)}	V _{GS} = -10 V	$V_{DS} \le -5 V$	-30	-	-	Α	
Drain-Source On-State Resistance ^a		$V_{GS} = -10 V$	I _D = -10 A	-	0.0070	0.0085	Ω	
	Б	$V_{GS} = -10 V$	I _D = -10 A, T _J = 125 °C	-	-	0.0130		
	R _{DS(on)}	V _{GS} = -10 V	I _D = -10 A, T _J = 175 °C	-	-	0.0150		
		$V_{GS} = -4.5 V$	I _D = -7 A	-	0.0120	0.0200		
Forward Transconductance b	g _{fs}	V _{DS} = -10 V, I _D = -10 A		-	32	-	S	
Dynamic ^b		<u>.</u>						
Output Capacitance	C _{oss}	$V_{GS} = 0 V$	V _{DS} = -15 V, f = 1 MHz	-	712	890	pF	
Total Gate Charge ^c	Qg) V V _{DS} = -15 V, I _D = -10 A	-	75	164	nC	
Gate-Source Charge ^c	Q _{gs}	V _{GS} = -10 V		-	9.5	-		
Gate-Drain Charge ^c	Q _{gd}			-	19	-		
Gate Resistance	Rg	f = 1 MHz		2	4.3	7.5	kΩ	
Turn-On Delay Time ^c	t _{d(on)}			-	38	57		
Rise Time ^c	t _r	$\label{eq:VDD} \begin{array}{l} V_{DD} = -15 \ V, \ R_L = 1.5 \ \Omega \\ I_D \cong -10 \ A, \ V_{GEN} = -10 \ V, \ R_g = 1 \ \Omega \end{array}$		-	82	123	ns	
Turn-Off Delay Time ^c	t _{d(off)}			-	134	201		
Fall Time ^c	t _f			-	178	214		
Source-Drain Diode Ratings and Chara	acteristics b	<u>.</u>						
Pulsed Current ^a	I _{SM}			-	-	-84	Α	
Forward Voltage	V _{SD}	$I_{\rm F} = -3$ A, $V_{\rm GS} = 0$ V		-	-0.75	-1.2	V	

Notes

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

c. Independent of operating temperature.

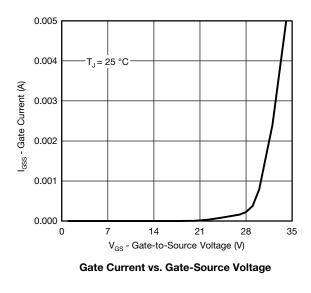
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

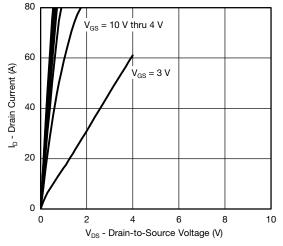
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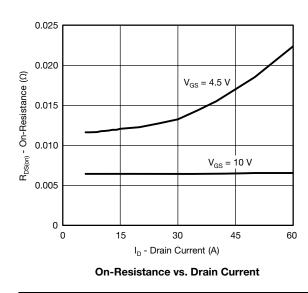
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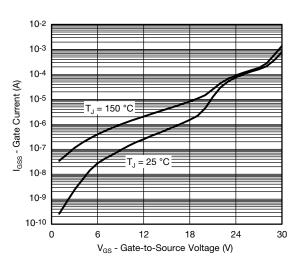
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



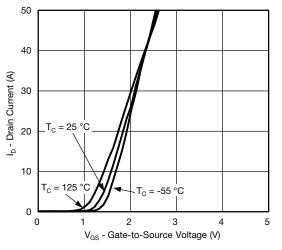




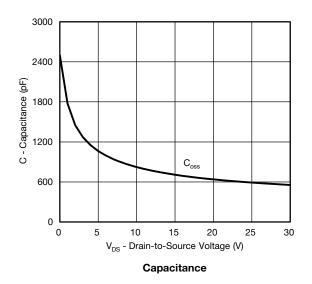




Gate Current vs. Gate-Source Voltage







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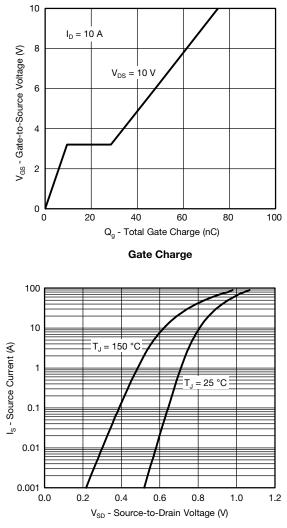
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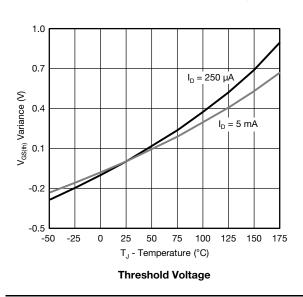


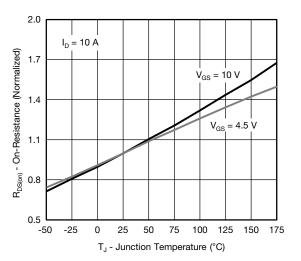
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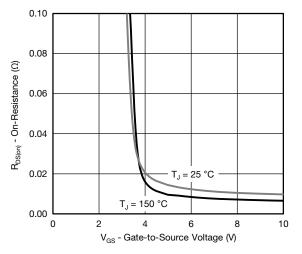


Source Drain Diode Forward Voltage

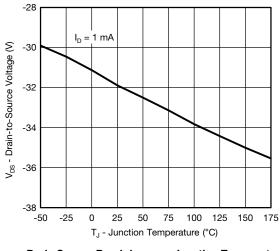




On-Resistance vs. Junction Temperature







Drain Source Breakdown vs. Junction Temperature

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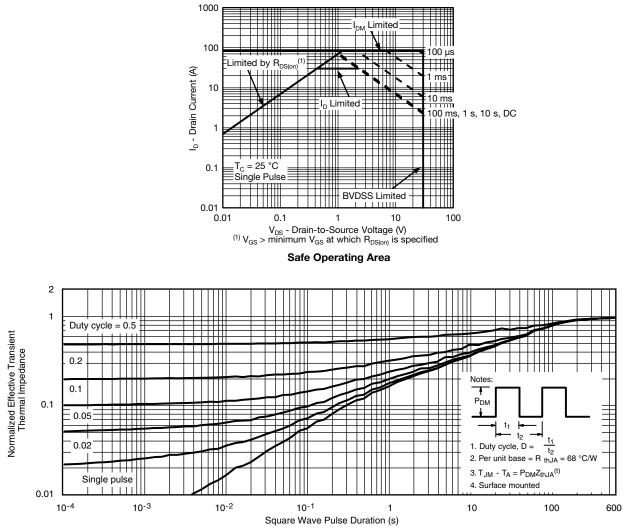
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THERMAL RATINGS ($T_A = 25 \text{ °C}$, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient

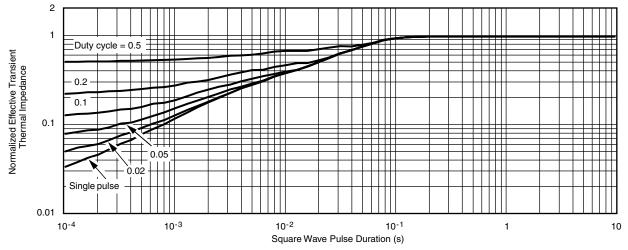


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THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

Note

• The characteristics shown in the two graphs

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- Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)

- Normalized Transient Thermal Impedance Junction-to-Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <u>www.vishay.com/ppg?67407</u>.



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